

High speed IGBT in Trench and Fieldstop Technology
■ Applications

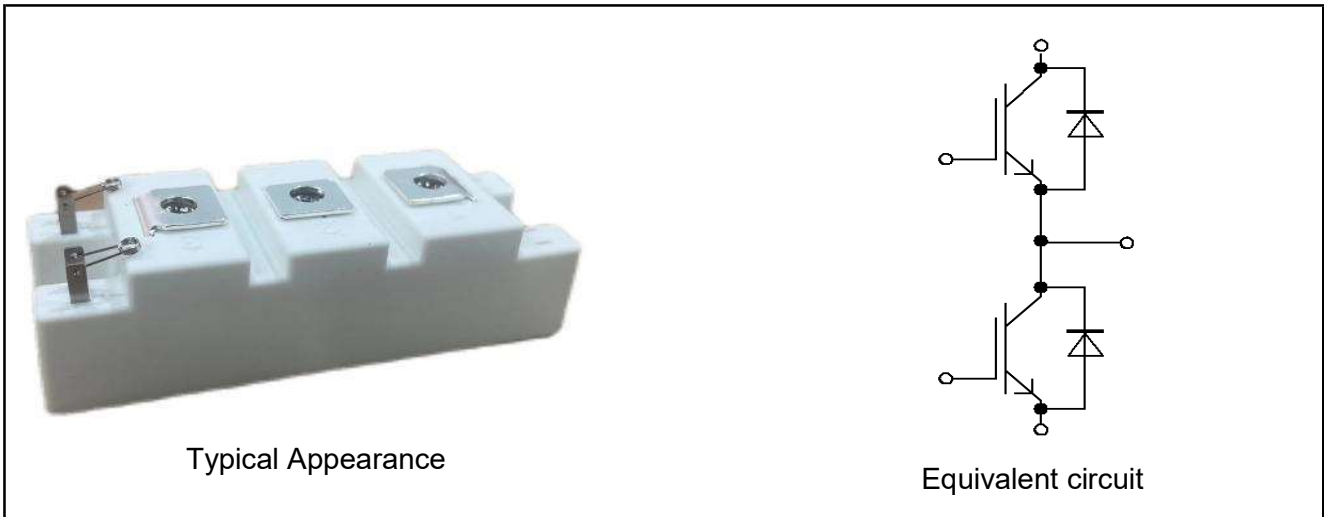
- Motor Drives
- Solar Applications
- UPS Systems
- HighPowerConverters

■ Features

- 1200V 100A, $V_{CE(sat)} = 1.7V@25^{\circ}C$
- High RBSOA Capability
- Trench/FS Technology
- Low Reverse-recovery Losses
- High SC Capability

■ Product Summary

V_{CES}	1200	V
I_C	100	A
$V_{CE(sat)}, Typ@15V$	1.7	V



Marking	Package	Packaging	Min. package quantity
MMA100HF120T7	34mm	Box-packed	8





■ Absolute Maximum Ratings (Tc=25°C unless otherwise noted)

Parameter	Symbol	Ratings	Unit
Collector-Emitter voltage	V_{CES}	1200	V
DC collector current, limited by T_{jmax} TC=25°C TC=100°C	I_C	200 100	A
Pulsed Collector Current	I_{CP}	200	A
Diode forward current, limited by T_{jmax} TC=25°C TC=100°C	I_F	200 100	A
Diode Pulsed current, t_p limited by T_{jmax}	$I_{F Pulse}$	200	A
Continuous Gate-emitter voltage	V_{GE}	±30	V
Short Circuit Withstand Time($V_{CC} \leq 600V$, $V_{GE} = 15V$)	T_{SC}	10	µs
Temperature under switching conditions	T_{vj}	-40-150	°C
Storage Temperature	T_{stg}	-40-125	°C

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings.

■ Thermal Characteristics

Parameter	Symbol	Max	Unit
Thermal Resistance, Per IGBT Junction to Case	$R_{\theta JC}$	0.15	°C/W
Thermal Resistance, Per Diodes Junction to Case	$R_{\theta JC}$	0.25	°C/W

Note: This transistor is sensitive to electrostatic discharge and should be handled with care.





■ Electrical Characteristics (Tc=25°C unless otherwise noted)

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Static Characteristics						
Drain-Source Breakdown Voltage	BV_{CES}	$V_{GE}=0V, I_C=200\mu A$	1200	-	-	V
Zero gate voltage collector current	I_{CES}	$V_{CE}=1200V, V_{GE}=0V$	-	-	200	μA
Gate-emitter leakage current	I_{GES}	$V_{GE}=\pm 20V, V_{CE}=0V$	-	-	± 300	nA
Gate-emitter threshold voltage	$V_{GE(TH)}$	$V_{CE}=10V, I_C=100mA$	6.2	6.7	7.2	V
Collector-emitter saturation voltage	$V_{CE(sat)}$	$V_{GE}=15V, I_C=100A$	-	1.7	2.1	V
		$T_j=125^\circ C$	-	2.08	-	V
Dynamic Characteristics						
Input Capacitance	C_{ies}	$V_{CE}=25V, V_{GE}=0V,$ $f=1.0MHz$	-	25	-	nF
Reverse Transfer Capacitance	C_{res}		-	0.13	-	nF
Gate charge	Q_G	$V_{CE}=600V, V_{GE}=15V$	-	950	-	nC
Internal Gate Resister	R_G		-	3	-	Ω





■ Switching Characteristic, Inductive Load, at $T_j=25^\circ\text{C}$

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
IGBT Switching Characteristics						
Turn-On Delay Time	$t_{d(on)}$	$V_{CC}= 600V$ $I_C= 100A$ $V_{GE}= 15V$ $R_G= 5\Omega$ Inductive load	-	0.2	-	us
Turn-On Rise Time	t_r		-	0.09	-	us
Turn-Off Delay Time	$t_{d(off)}$		-	0.23	-	us
Turn-Off Fall Time	t_f		-	0.15	-	us
Turn-on energy	E_{on}		-	6.38	-	mJ
Turn-off energy	E_{off}		-	5.26	-	mJ
Diode Characteristics						
Diode forward voltage	V_F	$I_F=100A$	-	2	2.5	mA
Reverse Recovery Charge	Q_{rr}	$I_F= 100A, V_R= 600V,$ $-diF/dt= 1200A/us$	-	4.35	-	uC
Reverse Recovery Energy	E_{rec}		-	1.81	-	mJ





■ IGBT Module

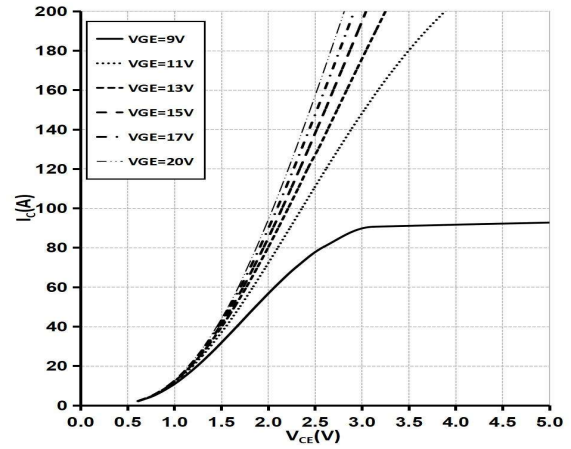
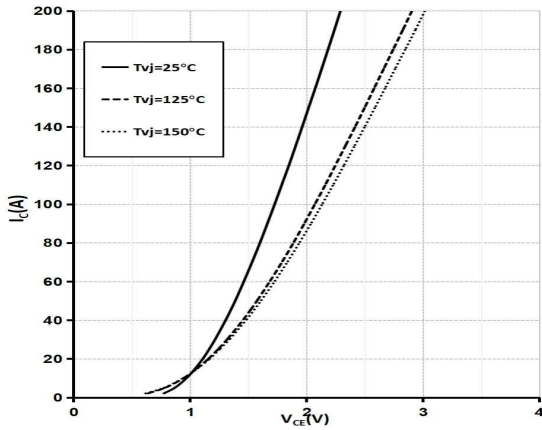
Parameter	Symbol	Test Condition	Values	Unit
Isolation test voltage	V_{ISOL}	RMS, f = 50Hz, t = 1 min	4	kV
Material of Module Base plat			Cu	
Internal Isolation			Al_2O_3	
Power Terminal Screw	d_{Creep}	Terminal to terminal	20.1	mm
Clearance	d_{Clear}	Terminal to terminal	9.5	mm
Comparative Tracking Index	CTI		200	

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Stray inductance module	L_{sCE}		-	29.2	-	nH
Module Lead Resistance, Terminals-Chip	R_{CC+EE}	$T_C = 25^{\circ}C$, Per switch	-	0.66	-	mΩ
Mounting Torque for Module Mounting	M	Screw M5	3	-	5	Nm
Weight of Module	G		-	156	-	g

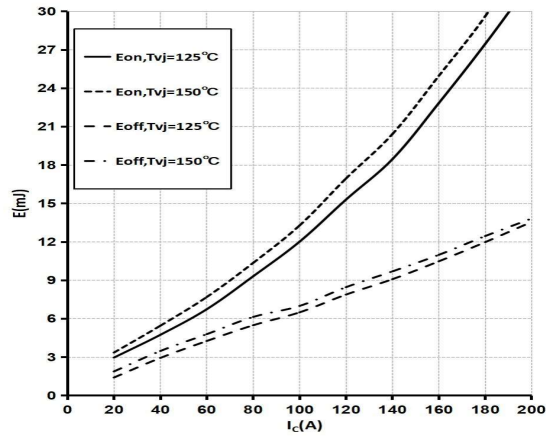




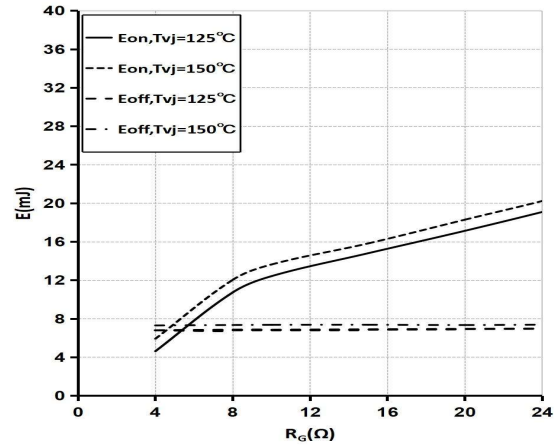
Characteristics Curves



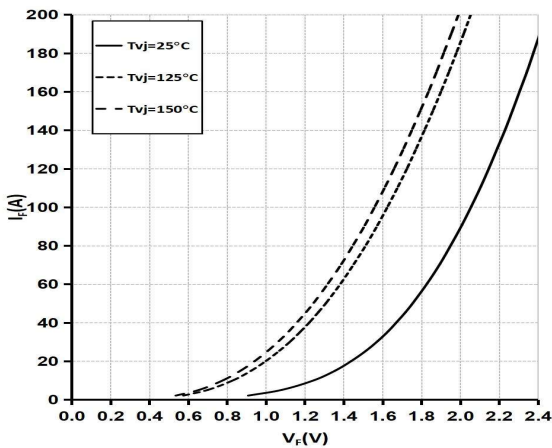
Output Characteristic, IGBT ($I_c = f(V_{CE}), V_{GE} = 15\text{V}$)



Output Characteristic, IGBT ($T_{vj}=150^\circ\text{C}$)

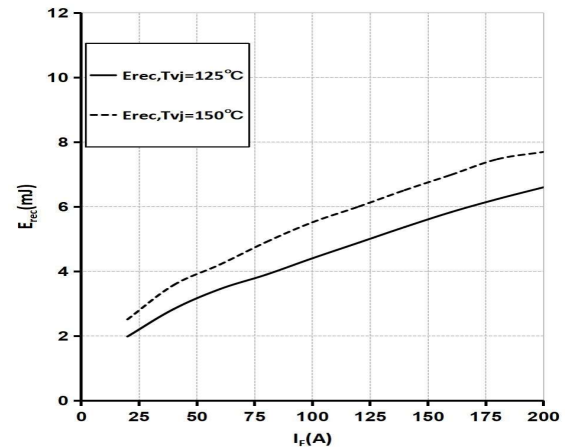


Switching losses (typical), IGBT ($E = f(I_c)$)
 $R_{Goff} = 10\Omega, R_{Gon} = 10\Omega, V_{GE} = \pm 15\text{V}, V_{CC} = 600\text{V}$



Forward characteristic (typical), Diode

Switching losses (typical), IGBT ($E = f(R_G), V_{GE} = 15\text{V}, I_c = 100\text{A}, V_{CC} = 600\text{V}$)

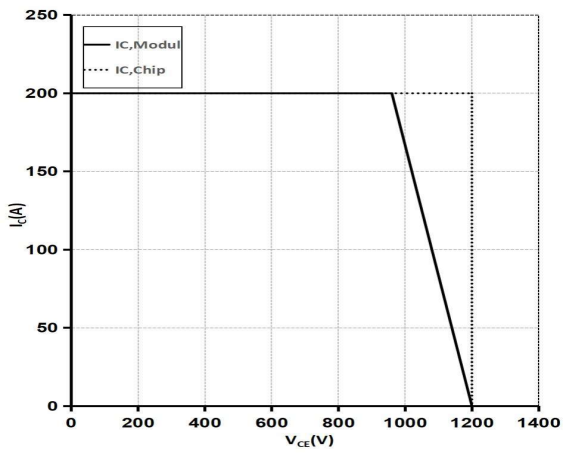


Switching losses (typical), Diode





■ Characteristics Curves



Reverse bias safe operating area (RBSOA), IGBT(I_C=
f(V_{CE}), R_{Goff}= 10Ω, V_{GE}= ±15V, T_{vj}= 150°C)

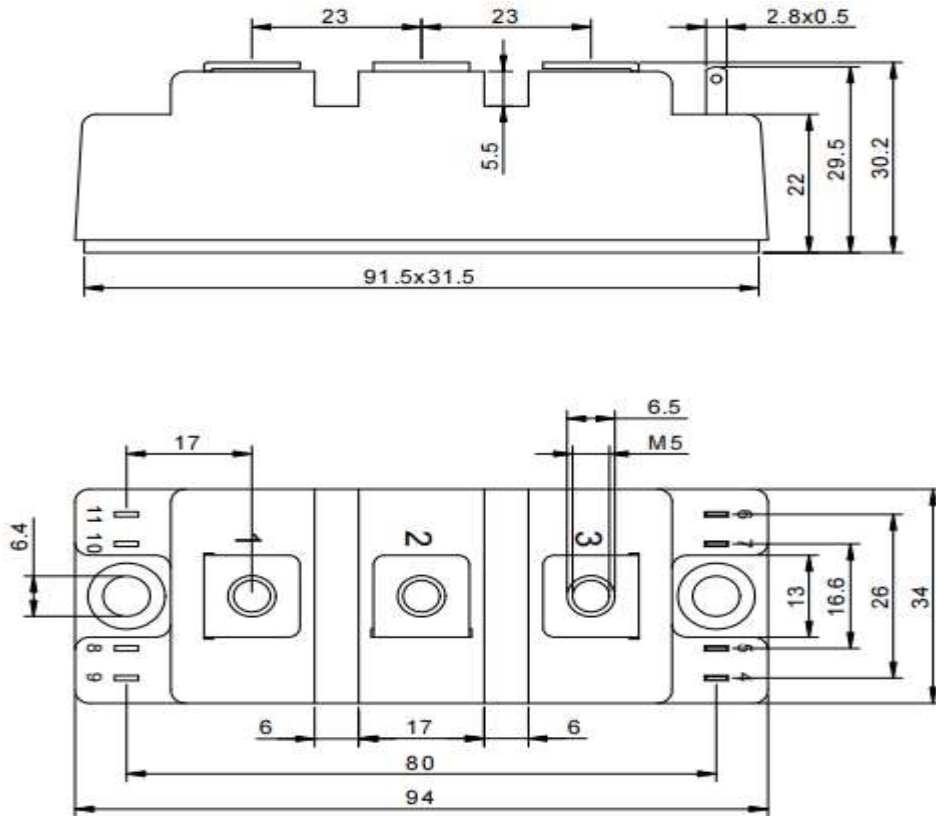




■ Package Dimension

Unit: mm

Dimensions in Millimeters



Circuit diagram headline

